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# N-Channel 600 V (D-S) MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	$R_{DS(on)}\left(\Omega\right)$	I <sub>D</sub> (A)			
600	80 at V <sub>GS</sub> = 10 V	0.15			

(SOT-23-3L)

## FEATURES

• DT-Trench Power MOSFET

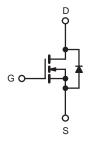


# Pb-free

RoHS

#### **APPLICATIONS**

- High efficient switched mode power supplies
- TV Power
- Adapter/charger



N-Channel MOSFET

D _ 3	
1	= 2
G	S
Top View	

<b>ABSOLUTE MAXIMUM RATINGS</b> T <sub>A</sub> = 25 °C, unless otherwise noted					
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		$V_{DS}$	600	V	
Gate-Source Voltage		$V_{GS}$	± 20	V	
Continuous Drain Current (T <sub>.I</sub> = 175 °C) <sup>a</sup>	T <sub>A</sub> = 25 °C	I <sub>D</sub>	0.15		
Continuous Diam Current (1) = 173 C)	T <sub>A</sub> = 70 °C	טי	0.13	Α	
Pulsed Drain Current		I <sub>DM</sub>	0.6	] ^	
Avalanche Current		I <sub>AS</sub>	0.12		
Peak diode recovery dv/dt		dv/dt	6	V/ns	
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> = 25 °C	P <sub>D</sub>	2.5	W	
Maximum Fower Dissipation	T <sub>A</sub> = 70 °C	. Б	1.86		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient <sup>a</sup>	t ≤ 10 s	R <sub>thJA</sub>	55	115		
Maximum Junction-to-Ambient	Steady State	'`thJA	38	85	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R <sub>thJF</sub>	12	28		

#### Notes:

a. Surface Mounted on 1" x 1" FR4 board.



<b>SPECIFICATIONS</b> T <sub>J</sub> = 25 °C, unless otherwise noted							
Parameter Symbo		Test Conditions Min.		Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	600			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I <sub>D</sub> = 250 μA		0.6		V/°C	
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2		4	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 600 \text{ V}, V_{GS} = 0 \text{ V}$			1	μA	
		V <sub>DS</sub> = 600 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C			10		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> = 5 V, V <sub>GS</sub> = - 10 V	19			Α	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = 10 \text{ V}, I_D = 0.02 \text{ A}$		80	120	Ω	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	$V_{DS} = 40 \text{ V}, I_{D} = 0.02 \text{ A}$		0.22		S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			73			
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 300 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		12		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			5			
Total Gate Charge	$Q_g$			3.9		nC	
Gate-Source Charge	Q <sub>gs</sub>	V <sub>DS</sub> = 300 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 0.02 A		0.28		nc nc	
Gate-Drain Charge	$Q_{gd}$			2.6			
Gate Resistance	$R_{g}$	f = 1 MHz		6.5		Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			7			
Rise Time	t <sub>r</sub>	$V_{DS} = 300 \text{ V}, R_{L} = 15 \Omega$		15		- ns	
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 0.02 \text{ A}, V_{GS} = 10 \text{ V}, R_g = 1 \Omega$		18			
Fall Time	t <sub>f</sub>			52			
Drain-Source Body Diode Characteristics							
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			0.15	A	
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>		_		0.6	^	
Body Diode Voltage	$V_{SD}$	I <sub>S</sub> = 0.15 A		0.8	1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			152		ns	
Body Diode Reverse Recovery Charge	by Diode Reverse Recovery Charge $Q_{rr}$ $I_F = 0.15 \text{ A}$ , $dI/dt = 100 \text{ A/µs}$ , $T_J = 25 ^{\circ}\text{C}$			165		nC	

#### Notes:

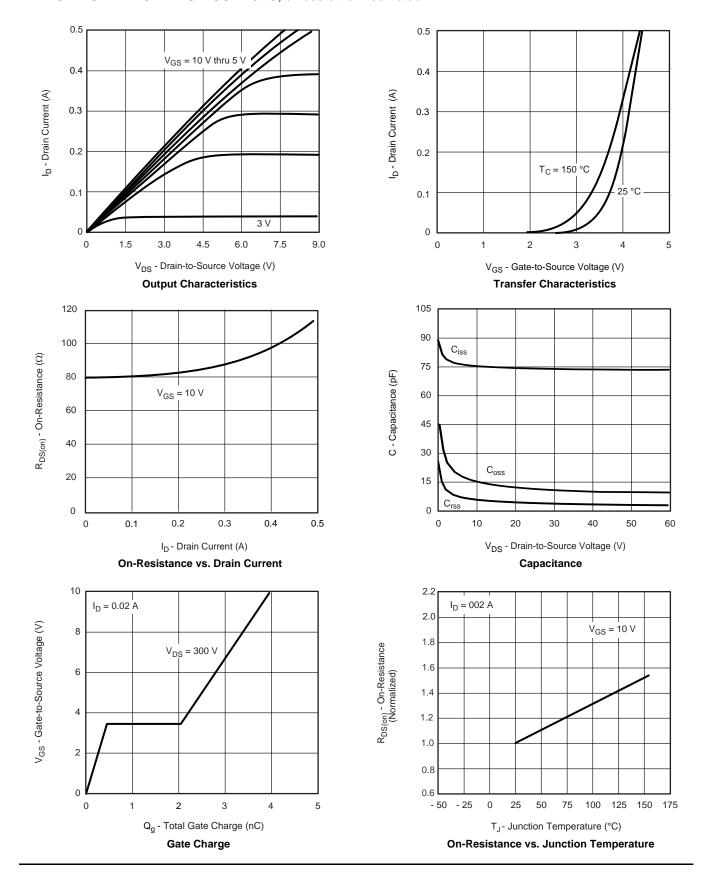
- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



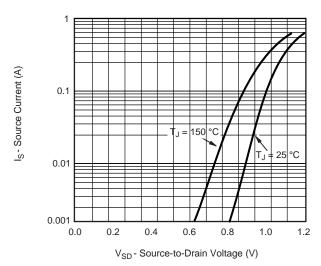


#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

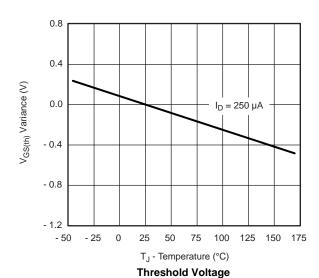


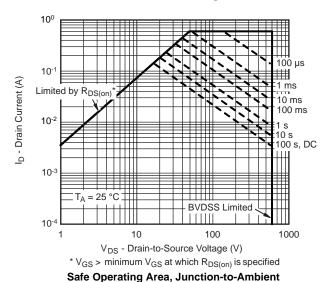


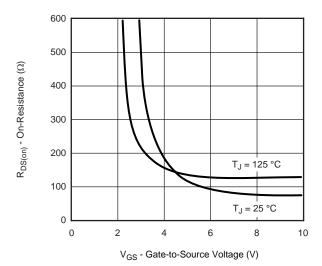
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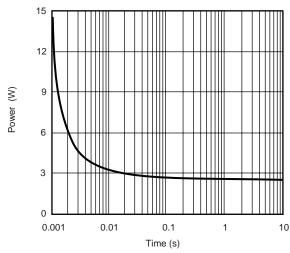
#### Source-Drain Diode Forward Voltage



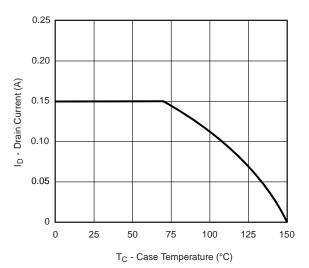




On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient

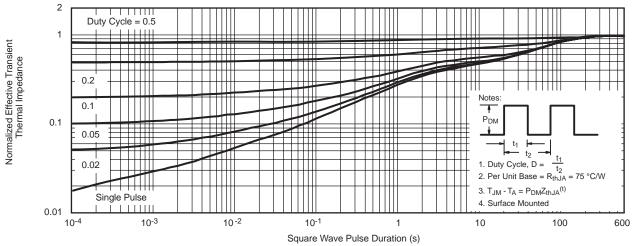


**Current Derating\*** 



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#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



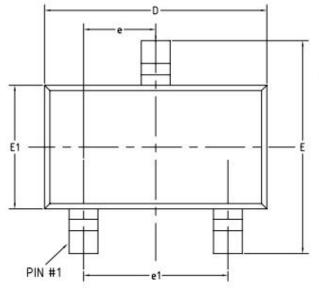
Normalized Thermal Transient Impedance, Junction-to-Ambient

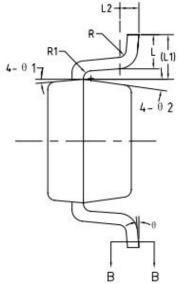
<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

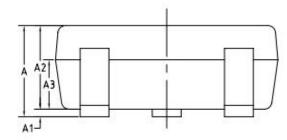




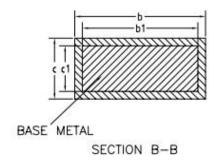
#### SOT-23-3L PACKAGE OUTLINE







# COMMON DIMENSIONS (UNITS OF MEASURE=MILLIMETER)



SYMBOL	MIN	TYP	MAX	
Α	1	ı	1.50	
A1	0.00	ı	0.18	
A2	0.85	1.10	1.35	
A3	0.58	0.65	0.72	
b	0.23	ı	0.53	
b1	0.20	0.40	0.50	
С	0.09	ı	0.22	
c1	0.08	0.13	0.21	
D	2.78	2.95	3.10	
Е	2.58	2.80	3.03	
E1	1.55	1.65	1.78	
е	0.83	0.95	1.07	
e1	1.78	1.90	2.02	
L	0.28	0.45	0.62	
L1	0.59REF			
L2	0.25BSC			
R	0.04	ı	-	
R1	0.04	-	0.21	
θ	0°	-	8°	
θ1	8°	10°	12°	
θ2	8°	10°	12°	





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